

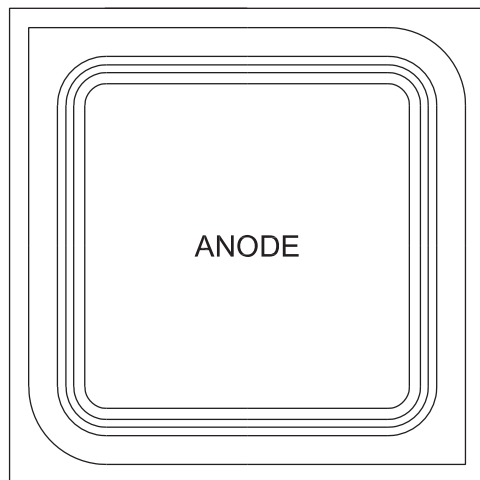
**PROCESS CPD94X**  
**Schottky Diode**  
0.5 Amp Schottky Diode Chip



**PROCESS DETAILS**

Die Size	20 x 20 MILS
Die Thickness	5.9 MILS
Anode Bonding Pad Area	16 x 16 MILS
Top Side Metalization	Al - 20,000Å
Back Side Metalization	Au - 12,000Å

**GEOMETRY**



BACKSIDE CATHODE R0

**GROSS DIE PER 5 INCH WAFER**

42,213

**PRINCIPAL DEVICE TYPES**

CMDSH05-4

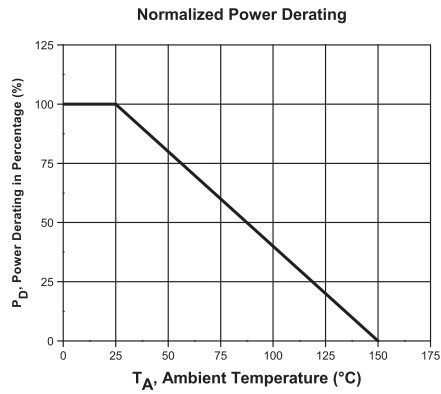
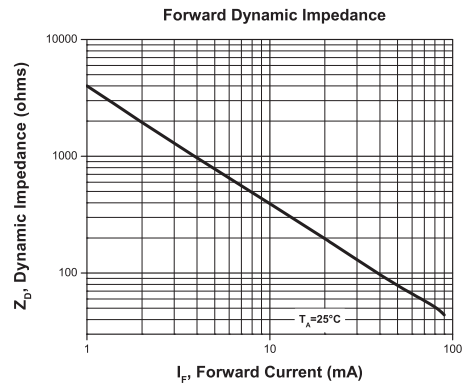
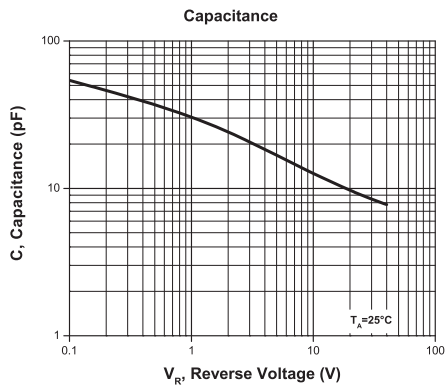
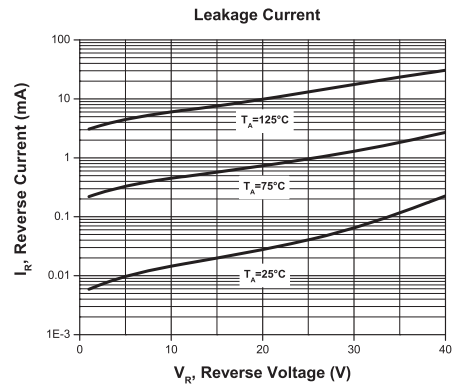
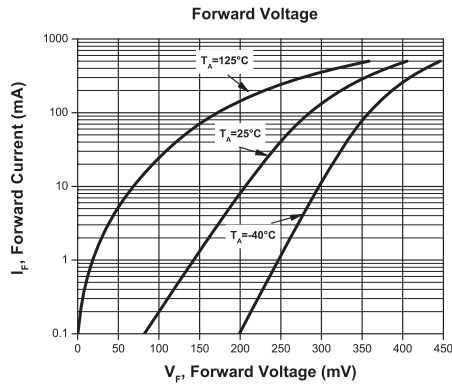
CMLSH05-4

CMPSH05-4

R0 (19-July 2010)

# PROCESS CPD94X

## Typical Electrical Characteristics



R0 (19-July 2010)